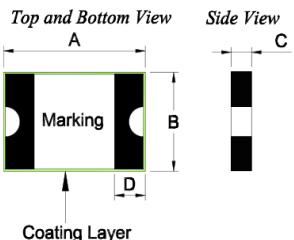


1、Physical Dimensions(size of 1812)

Unit:mm

Part Number	A*		B*		C		D	Marking
	Min	Max	Min	Max	Min	Max		
KMSML300/16	4.37	5.15	3.07	3.75	0.45	1.05	0.30	T300

* Dimension is measured after coating


2、Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} (Max time to trip)		P _{d typ} (W)	R _{min} (Ω)	R _{1 max} (Ω)
					Current (A)	Time (S)			
KMSML300/16	3.00	6.00	16	50	15.0	5.00	1.5	0.003	0.035

 I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

 I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

 V_{max}: Maximum voltage device can withstand without damage at rated current.

 I_{max}: Maximum fault current device can withstand without damage at rated voltage.

 T_{trip}: Maximum time to trip(s) at assigned current.

 P_{d typ}: Rated working power.

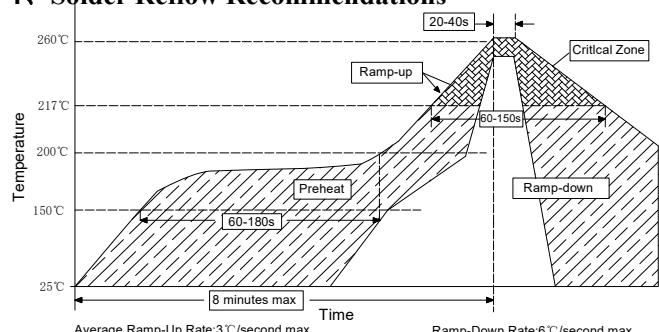
 R_{min}: Minimum resistance of device prior to trip at 25°C.

 R_{1 max}: Maximum resistance of device is measured one hours post reflow at 25°C.

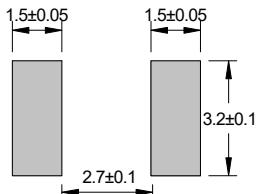
Noted: All electrical function test is conducted after PCB mounted.

3、Thermal Derating

KMSML300/16	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	4.38	3.85	3.51	3.00	2.62	2.31	2.08	1.82	1.54
Trip Current(A)	8.76	7.70	7.02	6.00	5.24	4.62	4.16	3.64	3.08

4、Solder Reflow Recommendations


Recommended Pad Layout(mm)



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、Package Information

Packing quantity:2000PCS/Reel

Note:Reel packaging per EIA-481-1 standard